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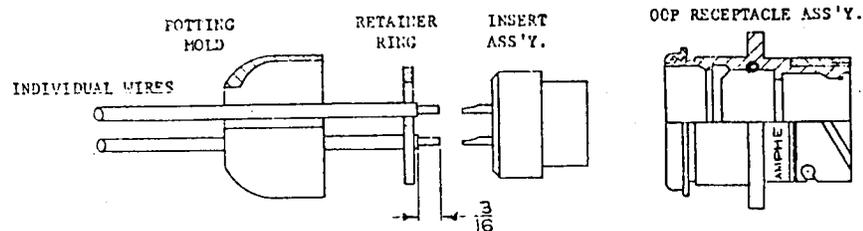
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## REVISIONS

SYM	ZONE	DESCRIPTION	DATE	APPROVED



DWG. NO. FIG 67-D

## WIRING TECHNIQUE:

1. Insert individual wires through potting mold.
2. Prepare individual wires for soldering by stripping insulation back to expose 3/16" of bare wire. Conductors may be solder tinned before they are soldered into the solder cups. This will permit easy entrance into the solder cups and will eliminate the possibility of loose strands.
3. Fill solder pockets with solder.
4. For easier soldering, position insert with open portion of solder pocket up. Begin soldering with the lowest row of contacts and work toward the top.
5. Slip wired insert assembly into the shell. Be sure to align keyway of insert with key lug in shell.
6. Retain insert assembly in shell by snapping in retainer ring.
7. Assemble potting mold onto shell assembly and fill with suitable potting compound.

## NOTE:

An alternate soldering method is to have the insert assembled into shell assembly and secured by the retainer ring prior to soldering.

ITEM NO.	PART OR IDENTIFYING NO.	QTY RECD	NOMENCLATURE OR DESCRIPTION
LIST OF MATERIALS OR PARTS LIST			
PART USED ON		DATE	AMPHENOL-CONNECTOR DIVISION-CENTRAL OPERATION AMPHENOL-BORG ELECTRONICS CORPORATION CHICAGO, ILLINOIS
DRAWN R. MARVAK		4-15-63	
CHECKED J.C. z X.		4-16-63	
APPROVED C. H.		7-16-63	TITLE
ENGINEERING RELEASE			METHOD FOR WIRING 67 SERIES OOP RECEPTACLES
MATERIAL No.			
INDUSTRIAL ENGRG APPD.			
DESIGN ACTIVITY APPD.			
FINISH		CODE IDENT NO.	DWG SIZE
EXPERIMENTAL NO.		02660	B
		DRAWING NO.	
		FIG 67-D	
		SCALE	SHEET

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